

RD Number: RD127

RD Title: TB67S128FTG Evaluation circuit

Item No.	Designator	Quantity	Value	Part Number	Manufacturer	Description	Package	Not Mount
1	CVM1	1	100uF	EKMG500ELL101MHB5D	NIPPON CHEMI-CON	Electrolytic capacitor		
2	CVM2	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		
3	CCPO	1	0.22uF	GCM31MR71H224KA37L		Ceramic capacitor		
4	CCP	1	0.022uF	GCM3195C1H223JA16D		Ceramic capacitor		
5	R_RSA	0	0.22Ω	ERJ-1TRQFR22U		Chip resistor		✓
6	R_RSB	0	0.22Ω	ERJ-1TRQFR22U		Chip resistor		✓
7	RS1	1				Short		
8	RS2	1				Short		
9	R_LTH	1	100kΩ	MFS1/4CC104F		Leaded resistor		
10		2	-	PD-10	Mac8	Socket pin		
11	R_VREF1	0				Leaded resistor		✓
12		2	-	PD-10	Mac8	Socket pin		
13	R_VREF2	0				Leaded resistor		✓
14		2	-	PD-10	Mac8	Socket pin		
15	R_BST1	1	100kΩ	RK73B2BTDD104J		Chip resistor		
16	R_BST2	1	100kΩ	RK73B2BTDD104J		Chip resistor		
17	R_FLM1	1	100kΩ	RK73B2BTDD104J		Chip resistor		
18	R_FLM2	1	100kΩ	RK73B2BTDD104J		Chip resistor		
19	R_CLIM11	1	100kΩ	RK73B2BTDD104J		Chip resistor		
20	R_CLIM12	1	100kΩ	RK73B2BTDD104J		Chip resistor		
21	R_OSC	1	5.1kΩ	RK73B2BTDD512J		Leaded resistor		
22		2	-	PD-10	Mac8	Socket pin		
23	C_OSC	1	270pF	GRM31A7U3A271JW31D		Ceramic capacitor		
24	R_MO	1	10kΩ	RK73B2BTDD103J		Chip resistor		
25	C_VCC	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		
26	C_VREF	1	0.1uF	GRM319R72A104KA01D		Ceramic capacitor		

27	C_VDD	1	10μF	ESRM160ELL100MD05D	NIPPON CHEMI-CON	Electrolytic capacitor		
28	R_LO0	1	10kΩ	RK73B2BTDD103J		Chip resistor		
29	R_LO1	1	10kΩ	RK73B2BTDD103J		Chip resistor		
30	C_OUTA+	0	1000pF			Ceramic capacitor		✓
31	C_OUTA-	0	1000pF			Ceramic capacitor		✓
32	C_OUTB-	0	1000pF			Ceramic capacitor		✓
33	C_OUTB+	0	1000pF			Ceramic capacitor		✓
34	SW1, SW2, SW17, SW18	4		XJ8B-0911	Omron	Jumper		
35		4		2180BAA	HARWIN	Short pin		
36	SW3~11,SW13~16,SW19	14	-	ATE1E-2M3-10-Z	NIDEC COPAL ELECTRONICS	Toggle switch		
37	SW22~24	3	-	S-2150	NIDEC COPAL ELECTRONICS	Rotary switch		
38	JP_VDD	1	-	2130S1*2GSE	Linkman	Jumper		
39		1		2180BAA	Linkman	Short pin		
40	CN1	1	-	DF1BZ-4P-2.5DSA	Hirose Electric	Connector		
41	OSCM	1	-	ST-1-3	Mac8	Check pin		
42	CLIM0	1	-	ST-1-3	Mac8	Check pin		
43	CLIM1	1	-	ST-1-3	Mac8	Check pin		
44	FLM	1	-	ST-1-3	Mac8	Check pin		
45	BST	1	-	ST-1-3	Mac8	Check pin		
46	IF_SEL	1	-	ST-1-3	Mac8	Check pin		
47	VCC	1	-	ST-1-3	Mac8	Check pin		
48	RSA	1	-	ST-1-3	Mac8	Check pin		
49	OUT_A+	1	-	ST-1-3	Mac8	Check pin		
50	OUT_A-	1	-	ST-1-3	Mac8	Check pin		
51	OUT_B-	1	-	ST-1-3	Mac8	Check pin		
52	OUT_B+	1	-	ST-1-3	Mac8	Check pin		
53	RSB	1	-	ST-1-3	Mac8	Check pin		
54	VM	1	-	ST-1-3	Mac8	Check pin		
55	MDT0	1	-	ST-1-3	Mac8	Check pin		
56	MDT1	1	-	ST-1-3	Mac8	Check pin		
57	TORQE0	1	-	ST-1-3	Mac8	Check pin		
58	TORQE1	1	-	ST-1-3	Mac8	Check pin		
59	TORQE2	1	-	ST-1-3	Mac8	Check pin		

60	AGC	1	-	ST-1-3	Mac8	Check pin		
61	MODE0	1	-	ST-1-3	Mac8	Check pin		
62	MODE1	1	-	ST-1-3	Mac8	Check pin		
63	MODE2	1	-	ST-1-3	Mac8	Check pin		
64	CLK	1	-	ST-1-3	Mac8	Check pin		
65	CW/CCW	1	-	ST-1-3	Mac8	Check pin		
66	STANDBY	1	-	ST-1-3	Mac8	Check pin		
67	ENABLE	1	-	ST-1-3	Mac8	Check pin		
68	RESET	1	-	ST-1-3	Mac8	Check pin		
69	GAIN_SEL	1	-	ST-1-3	Mac8	Check pin		
70	EDG_SEL	1	-	ST-1-3	Mac8	Check pin		
71	LO0	1	-	ST-1-3	Mac8	Check pin		
72	LO1	1	-	ST-1-3	Mac8	Check pin		
73	MO	1	-	ST-1-3	Mac8	Check pin		
74	GND	10	-	ST-1-3	Mac8	Check pin		
75	VREF	1	-	ST-1-3	Mac8	Check pin		
76	RS_SEL	1	-	ST-1-3	Mac8	Check pin		
77	VDD	1	-	ST-1-3	Mac8	Check pin		
78	OUT_A+_1	1	-	ST-1-3	Mac8	Check pin		
79	OUT_A-_1	1	-	ST-1-3	Mac8	Check pin		
80	OUT_B-_1	1	-	ST-1-3	Mac8	Check pin		
81	OUT_B+_1	1	-	ST-1-3	Mac8	Check pin		
82	VM_1	1	-	ST-1-3	Mac8	Check pin		
83	CP-	1	-	ST-1-3	Mac8	Check pin		
84	CP+	1	-	ST-1-3	Mac8	Check pin		
85	CP0	1	-	ST-1-3	Mac8	Check pin		
86	IC	1	-	TB67S128FTG	Toshiba	IC		
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